

Ultraform® H 2320 006 UNC Q600 Polyoxymethylene



Product Description

Ultraform H 2320 006 UNC Q600 is a POM with high molecular weight grade for injection molding.

Applications

Typical applications include thick-walled articles.

PHYSICAL	ISO Test Method	Property Value
Density, g/cm ³	1183	1.40
Mold Shrinkage, parallel, %	294-4	2.1
Mold Shrinkage, normal, %	294-4	2.1
Moisture, %	62	
(50% RH)		0.2
(Saturation)		0.8
RHEOLOGICAL	ISO Test Method	Property Value
Melt Volume Rate (190 C/2.16 Kg), cc/10min.	1133	2.9
MECHANICAL	ISO Test Method	Property Value
Tensile Modulus, MPa	527	
23C		2,600
Tensile stress at yield, MPa	527	
23C		64
80C		33
Tensile strain at yield, %	527	
23C		11
Nominal strain at break, %	527	
23C		30
Flexural Modulus, MPa	178	
23C		2,600
Tensile Creep Modulus (1000h), MPa	899	1,300
Tensile Creep Modulus (1h), MPa	899	1,800
IMPACT	ISO Test Method	Property Value
Izod Notched Impact, kJ/m ²	180	
-40C		5
23C		6
Charpy Notched, kJ/m ²	179	
-30C		5.5
23C		6
Charpy Unnotched, kJ/m ²	179	
-30C		200
23C		260
THERMAL	ISO Test Method	Property Value
Melting Point, C	3146	166
HDT A, C	75	95

HDT B, C	75	156
Coef. of Linear Thermal Expansion, Parallel, mm/mm C		1.1 X10-4

ELECTRICAL	ISO Test Method	Property Value
Comparative Tracking Index	IEC 60112	600
Volume Resistivity (Ohm-m)	IEC 60093	1E13
Surface Resistivity (Ohm)	IEC 60093	1E13
Dielectric Constant (100 Hz)	IEC 60250	3.8
Dielectric Constant (1 MHz)	IEC 60250	3.8
Dissipation Factor (100 Hz), E-4	IEC 60250	10
Dissipation Factor (1 MHz), E-4	IEC 60250	50
Dielectric Strength, KV/mm	IEC 60243-1	40

Processing Guidelines

Material Handling

Max. Water content: 0.15%

Product is supplied in polyethylene bags and drying prior to molding is not required. However, after relatively long storage or when handling material from previously opened containers, preliminary drying is recommended in order to remove any moisture which has been absorbed. If drying is required, a dehumidifying or desiccant dryer operating at 80 - 110C (176 - 230F) is recommended. Drying time is dependent on moisture level, however 2-4 hours is generally sufficient. Further information concerning safe handling procedures can be obtained from the Safety Data Sheet. Alternatively, please contact your BASF representative.

Typical Profile

Melt Temperature 190-230C (375-446F)

Mold Temperature 60-120C (140-248F)

Injection and Packing Pressure 35-70 bar (500-1000psi)

Mold Temperatures

A mold temperature of 80-90C (176-194F) is recommended, however temperatures of as low as 45C (113F) and as high as 105C (221F) can be used where applicable.

Pressures

Injection speed must be optimized. A filling rate which is too high results in anisotropic mechanical properties, while a filling rate which is too low yields parts with poor surface finish. The tool must be vented to avoid burn marks and prevent mold deposits. Injection pressure controls the filling of the part and should be applied for 90% of ram travel. Packing pressure affects the final part and can be used effectively in controlling sink marks and shrinkage. It should be applied and maintained until the gate area is completely frozen off.

Back pressure can be utilized to provide uniform melt consistency and reduce trapped air and gas.

Fill Rate

Injection speed must be optimized. A filling rate which is too high results in anisotropic mechanical properties, while a filling rate which is too low yields parts with poor surface finish. The tool must be vented to avoid burn marks and prevent mold deposits.

Note

Note

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